

SK100GB066T



SEMITOP[®] 3

IGBT Module

SK100GB066T

Target Data

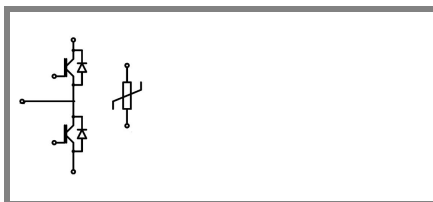
Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Trench IGBT technology
- CAL technology FWD
- Integrated NTC temperature sensor

Typical Applications*

Remarks

- $V_{isol} = 3000V$ AC, 50Hz, 1s

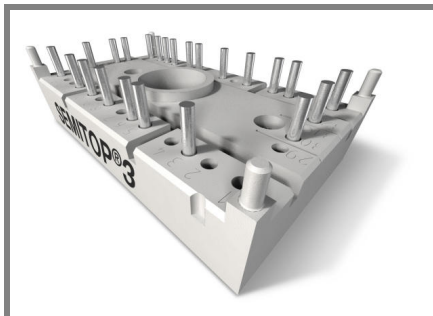


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Absolute Maximum Ratings		$T_s = 25\text{ °C}$, unless otherwise specified			
Symbol	Conditions	Values			Units
IGBT					
V_{CES}	$T_j = 25\text{ °C}$	600			V
I_C	$T_j = 175\text{ °C}$	$T_s = 25\text{ °C}$	96		A
		$T_s = 70\text{ °C}$	75		A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	200			A
V_{GES}		± 20			V
t_{psc}	$V_{CC} = 360\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 150\text{ °C}$ $V_{CES} < 600\text{ V}$	6			μs
Inverse Diode					
I_F	$T_j = 175\text{ °C}$	$T_s = 25\text{ °C}$	108		A
		$T_s = 70\text{ °C}$	84		A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	200			A
Module					
$I_{t(RMS)}$					A
T_{vj}		-40 ... +175			$^{\circ}\text{C}$
T_{stg}		-40 ... +125			$^{\circ}\text{C}$
V_{isol}	AC, 1 min.	2500			V

Characteristics		$T_s = 25\text{ °C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 1,6\text{ mA}$	5	5,8	6,5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$	$T_j = 25\text{ °C}$	0,0026		mA
		$T_j = 125\text{ °C}$			mA
I_{GES}	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}$	$T_j = 25\text{ °C}$	1200		nA
V_{CE0}		$T_j = 25\text{ °C}$	0,8	1,1	V
		$T_j = 125\text{ °C}$	0,7	1	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25\text{ °C}$	6,5	8	$\text{m}\Omega$
		$T_j = 150\text{ °C}$	9,5	10,5	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 100\text{ A}, V_{GE} = 15\text{ V}$	$T_j = 25\text{ °C}_{chiplev.}$	1,45	1,85	V
		$T_j = 150\text{ °C}_{chiplev.}$	1,65	2,05	V
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	6,28		nF
C_{oes}			0,4		nF
C_{res}			0,19		nF
Q_G	$V_{GE} = -7V...+15V$	1000			nC
$t_{d(on)}$	$R_{Gon} = 32\ \Omega$ $di/dt = 2575\text{ A}/\mu\text{s}$	$V_{CC} = 300V$ $I_C = 100A$	144		ns
t_r			128		ns
E_{on}			7		mJ
$t_{d(off)}$	$R_{Goff} = 32\ \Omega$ $di/dt = 2575\text{ A}/\mu\text{s}$	$T_j = 150\text{ °C}$ $V_{GE} = -7/+15V$	1040		ns
t_f			91		ns
E_{off}			6		mJ
$R_{th(j-s)}$	per IGBT	0,78			K/W

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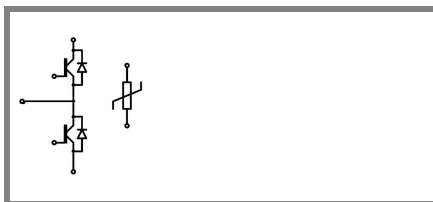
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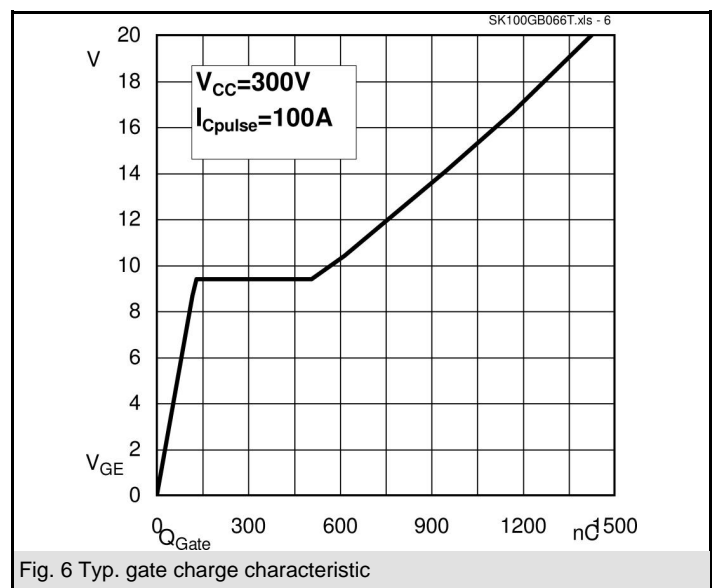
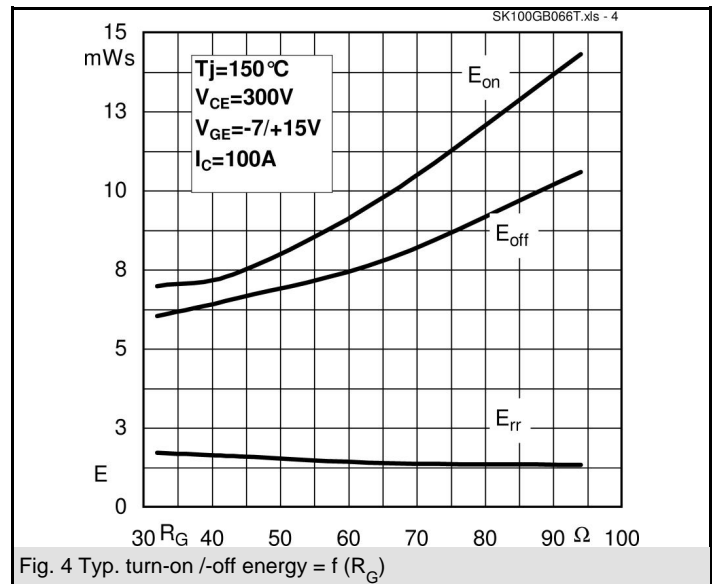
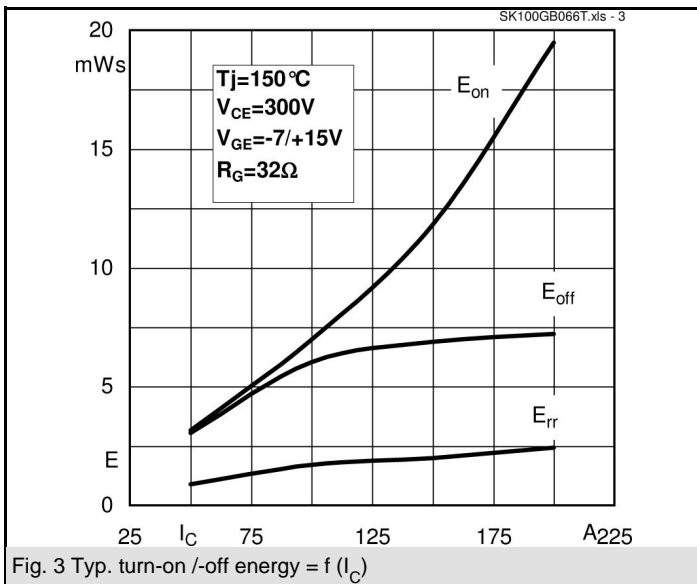
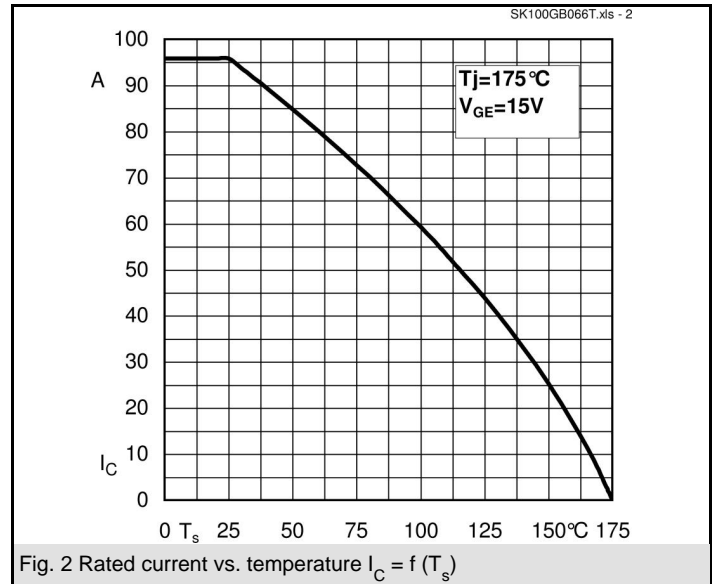
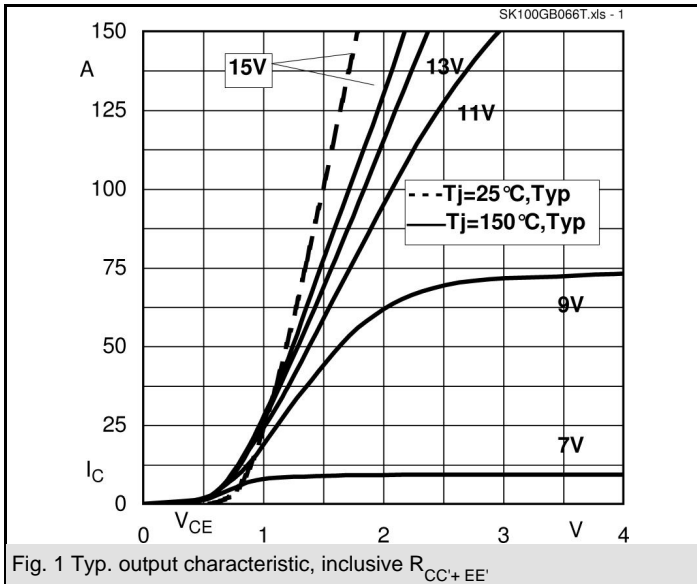
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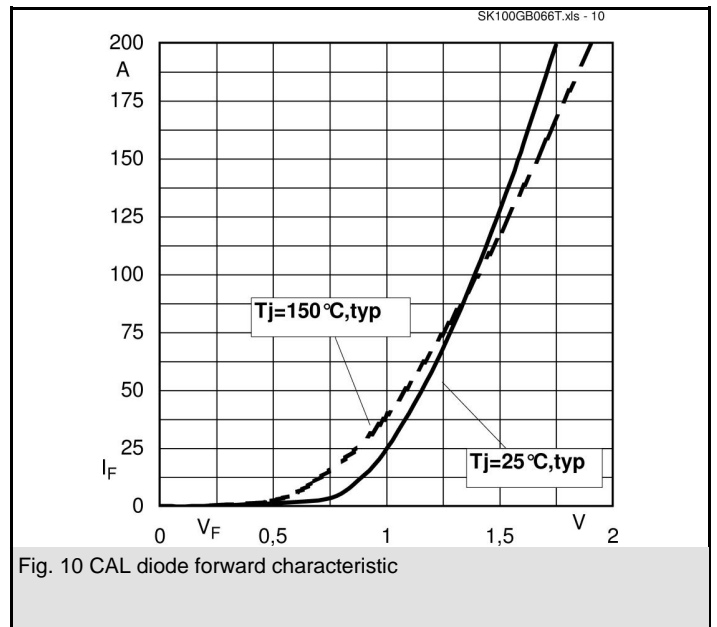
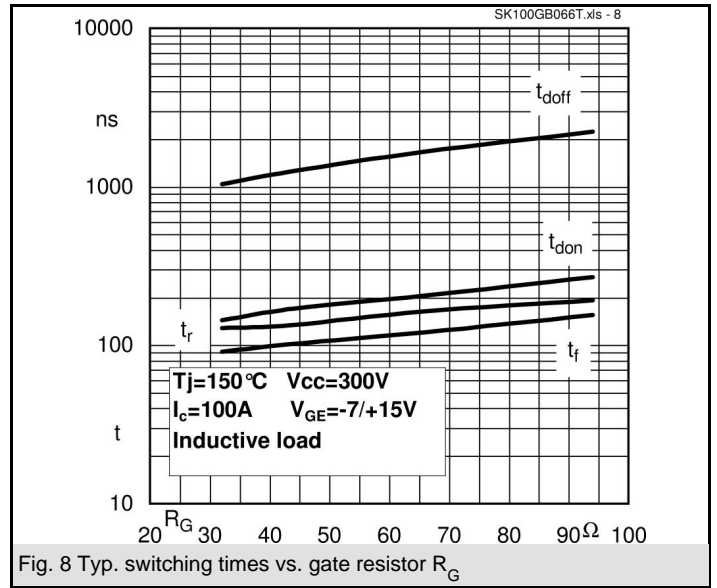
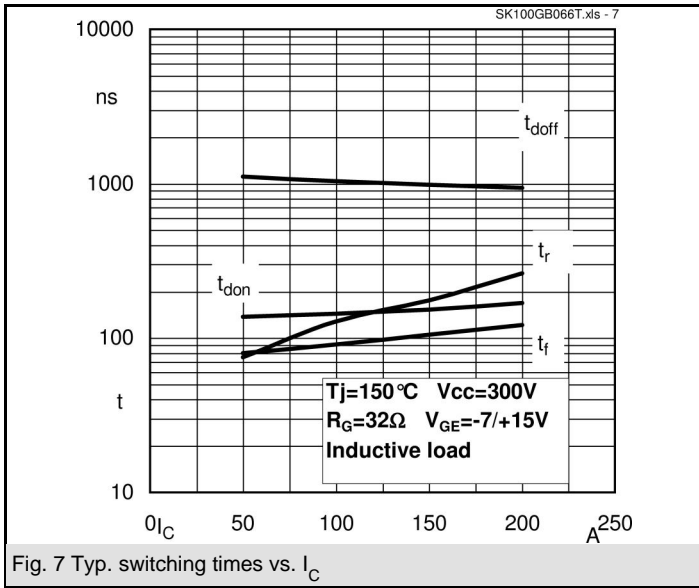
Characteristics

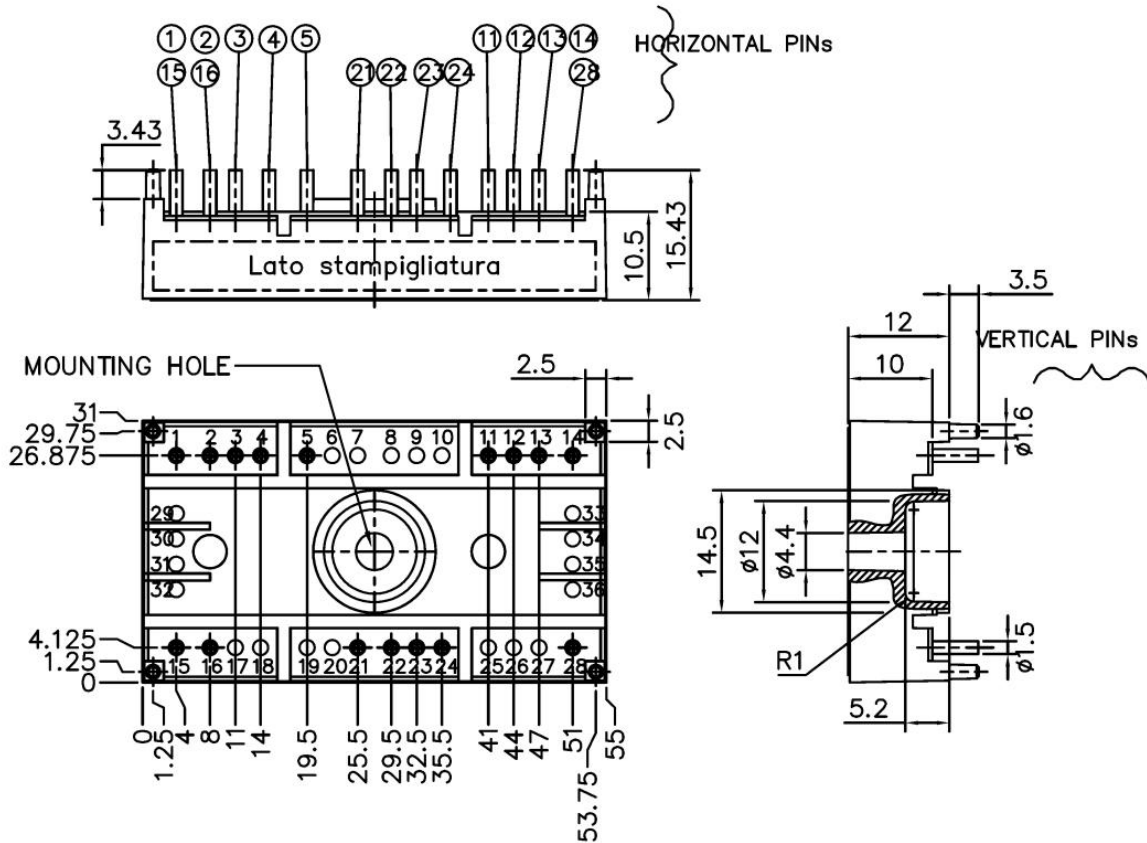
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 100 A; V_{GE} = 0 V$				
	$T_j = 25\text{ }^{\circ}C_{chiplev.}$		1,35		V
	$T_j = 150\text{ }^{\circ}C_{chiplev.}$		1,31		V
V_{F0}					V
	$T_j = 25\text{ }^{\circ}C$				V
	$T_j = 150\text{ }^{\circ}C$		0,85		V
r_F					mΩ
	$T_j = 25\text{ }^{\circ}C$				mΩ
	$T_j = 150\text{ }^{\circ}C$		6,3		mΩ
I_{RRM}	$I_F = 100 A$		60		A
Q_{rr}	$di/dt = 2575 A/\mu s$		5,6		μC
E_{rr}	$V_R = 300V$		1,7		mJ
$R_{th(j-s)D}$	per diode		0,91		K/W
Freewheeling Diode					
$V_F = V_{EC}$	$I_{Fnom} = A; V_{GE} = V$				V
	$T_j = \text{ }^{\circ}C_{chiplev.}$				V
V_{F0}					V
	$T_j = \text{ }^{\circ}C$				V
r_F					V
	$T_j = \text{ }^{\circ}C$				V
I_{RRM}	$I_F = A$				A
Q_{rr}					μC
E_{rr}	$V_R = 300V$				mJ
$R_{th(j-s)FD}$	per diode				K/W
M_s	to heat sink	2,5		2,75	Nm
w			60		g
Temperature sensor					
R_{100}	$T_s = 100\text{ }^{\circ}C (R_{25} = 5k\Omega)$		493±5%		Ω

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.







Case T 73 (Suggested hole diameter for the solder pins in the circuit board: 2mm. Suggested hole diameter for the mounting pins in the circuit board: 3,6mm)

